

Material Set Change:

Package Material Set		Carsem	ASE Chungli
QSOP	Die Attach	Ablestik 84-1LMISR4	Hitachi EN4900GC
	Mold Compound	Sumitomo G600C	Sumitomo G700LY
	Wire	1.0mil Gold Wire	1.0mil Gold Wire

**Addition of ASE Chungli as an Alternate Assembly Site
for Select Isolator Products in 16L and 20L QSOP**

**Automotive Qualification Results Summary
of QSOP at ASE Chungli**

QUALIFICATION RESULT			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A112</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS

*These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C. TC samples are subjected to wire-pull test after 500 cycles with results within specification limits.